

Electronic Acknowledgement Receipt

EFS ID:	5531117
Application Number:	10577173
International Application Number:	
Confirmation Number:	1239
Title of Invention:	Semiconductor device with plastic package molding compound, semiconductor chip and leadframe and method for producing the same
First Named Inventor/Applicant Name:	Infineon Technologies AG
Customer Number:	25281
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Filer Authorized By:	Mark L. Gleason
Attorney Docket Number:	I441.141.101
Receipt Date:	17-JUN-2009
Filing Date:	
Time Stamp:	11:28:58
Application Type:	U.S. National Stage under 35 USC 371

Payment information:

Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Information Disclosure Statement (IDS) Filed (SB/08)	SupplDS.pdf	761670 890ec2f3a30729299a61669639f7fb8ffcabb3fd	no	4

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2	Foreign Reference	JP1264230uspto.pdf	372520	no	6
			1299caee13c28572e579ee2111bfb1415c5524ed		

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National Stage of an International Application under 35 U.S.C. 371

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New International Application Filed with the USPTO as a Receiving Office

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